

## N -Channel Enhancement Mode Power MOSFET

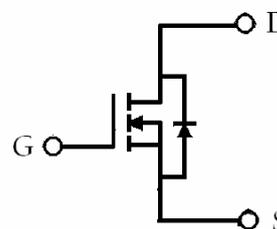
### Features:

- Low Gate Charge
- Simple Drive Requirement
- RoHS compliant & Halogen-free package

TO-252(DPAK)



$BV_{DSS}$	60V
$I_D$	16A
$R_{DSON(MAX)}@V_{GS}=10V, I_D=10A$	35m $\Omega$ (typ.)
$R_{DSON(MAX)}@V_{GS}=5V, I_D=8A$	40m $\Omega$ (typ.)



G : Gate D : Drain S :  
Source

### Ordering Information

Device	Package	Shipping
KJB60N06	TO-252 (RoHS compliant & Halogen-free package)	2500 pcs / Tape & Reel

**Absolute Maximum Ratings** (T<sub>c</sub>=25°C, unless otherwise noted)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	
Continuous Drain Current @ T <sub>c</sub> =25°C, V <sub>GS</sub> =10V	I <sub>D</sub>	16	A
Continuous Drain Current @ T <sub>c</sub> =100°C, V <sub>GS</sub> =10V	I <sub>D</sub>	10	
Pulsed Drain Current *1	I <sub>DM</sub>	30	
Avalanche Current	I <sub>AS</sub>	16	
Avalanche Energy @ L=0.1mH, I <sub>D</sub> =16A, R <sub>G</sub> =25 Ω	E <sub>AS</sub>	12.8	mJ
Repetitive Avalanche Energy @ L=0.05mH *2	E <sub>AR</sub>	3.6	
Total Power Dissipation @T <sub>c</sub> =25°C	P <sub>d</sub>	20	W
Total Power Dissipation @T <sub>c</sub> =100°C		8	
Operating Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55~+150	°C

Note : \*1. Pulse width limited by maximum junction temperature  
 \*2. Duty cycle ≤ 1%

**Thermal Data**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	R <sub>th,j-c</sub>	6.25	°C/W
Thermal Resistance, Junction-to-ambient, max	R <sub>th,j-a</sub>	110	°C/W

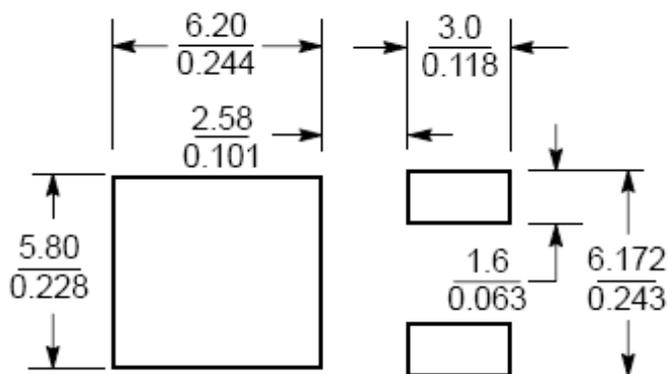
**Characteristics (T<sub>c</sub>=25°C, unless otherwise specified)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>					
BV <sub>DSS</sub>	60	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> =250μA
V <sub>GS(th)</sub>	1.0	1.7	3.0	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
G <sub>FS</sub> *1	-	10	-	S	V <sub>DS</sub> =5V, I <sub>D</sub> =10A
I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> =±20, V <sub>DS</sub> =0
I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =48V, V <sub>GS</sub> =0
	-	-	25	μA	V <sub>DS</sub> =40V, V <sub>GS</sub> =0, T <sub>j</sub> =125°C
I <sub>D(ON)</sub> *1	12	-	-	A	V <sub>DS</sub> =10V, V <sub>GS</sub> =10V
R <sub>DS(ON)</sub> *1	-	35	50	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =10A
	-	40	55	mΩ	V <sub>GS</sub> =5V, I <sub>D</sub> =8A
<b>Dynamic</b>					
Q <sub>g</sub> *1, 2	-	11	-	nC	I <sub>D</sub> =10A, V <sub>DS</sub> =20V, V <sub>GS</sub> =10V
Q <sub>gs</sub> *1, 2	-	2.2	-		
Q <sub>gd</sub> *1, 2	-	4.2	-		
t <sub>d(ON)</sub> *1, 2	-	11.7	-	ns	V <sub>DS</sub> =20V, I <sub>D</sub> =1A, V <sub>GS</sub> =10V, R <sub>G</sub> =6Ω
t <sub>r</sub> *1, 2	-	5.2	-		
t <sub>d(OFF)</sub> *1, 2	-	18	-		

$t_f$ *1, 2	-	6	-		
Ciss	-	1165	-	pF	$V_{GS}=0V, V_{DS}=20V, f=1MHz$
Coss	-	56	-		
Crss	-	43	-		
Rg	-	2.5	-	$\Omega$	$V_{GS}=15mV, V_{DS}=0, f=1MHz$
<b>Source-Drain Diode</b>					
$I_S$ *1	-	-	12	A	
$I_{SM}$ *3	-	-	48		
$V_{SD}$ *1	-	0.87	1.3	V	$I_F=I_S, V_{GS}=0V$
trr	-	16	-	ns	$I_F=5A, dI_F/dt=100A/\mu s$
Qrr	-	8	-	nC	

Note : \*1.Pulse Test : Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$   
 \*2.Independent of operating temperature  
 \*3.Pulse width limited by maximum junction temperature.

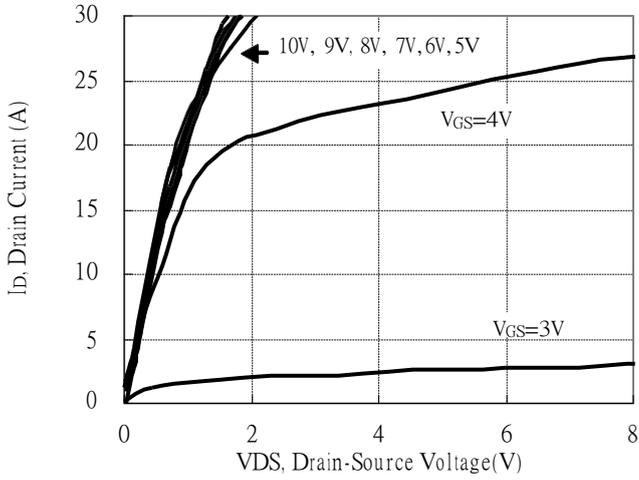
**Recommended soldering footprint**



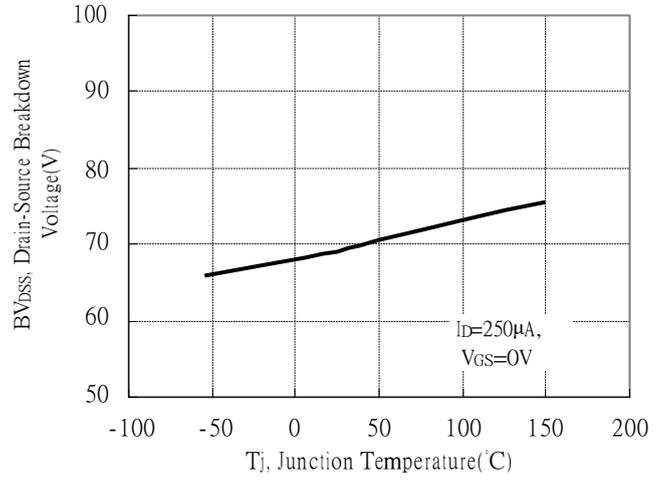
Unit (  $\frac{mm}{inch}$  )

### Typical Characteristics

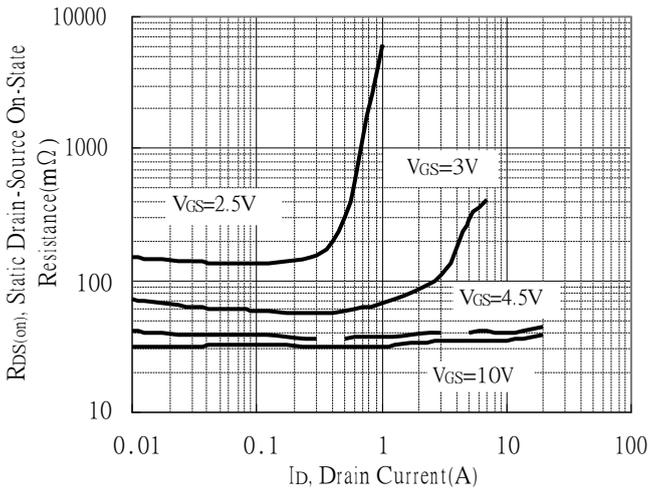
Typical Output Characteristics



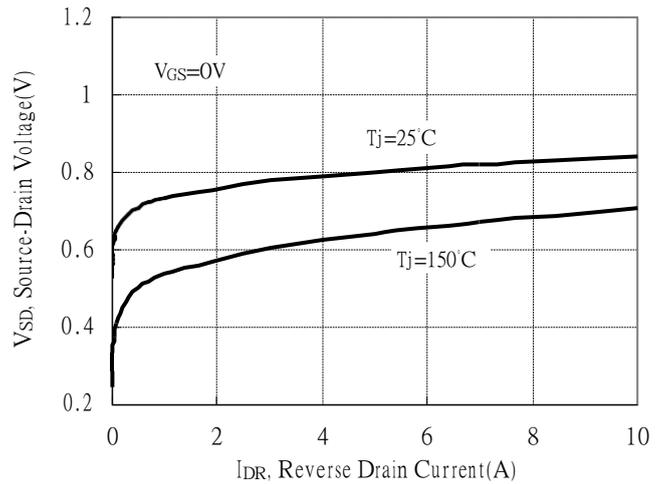
Breakdown Voltage vs Ambient Temperature



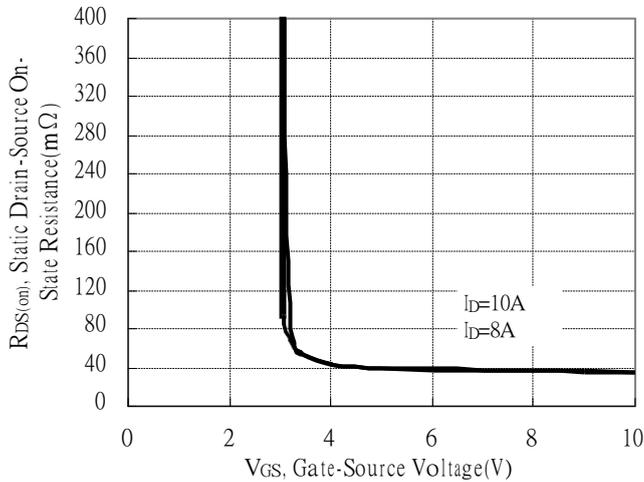
Static Drain-Source On-State resistance vs Drain Current



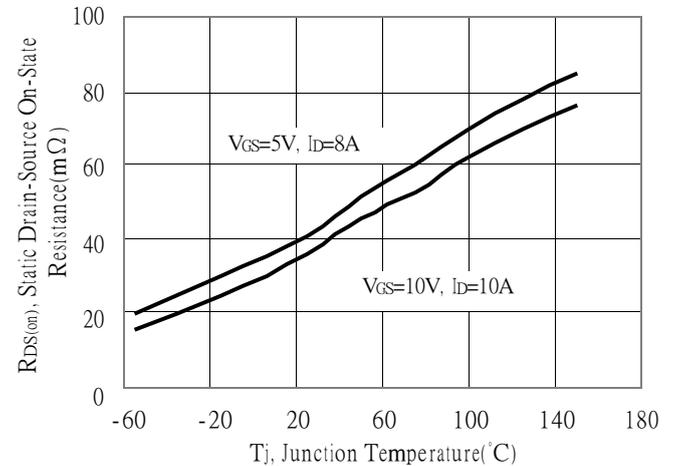
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

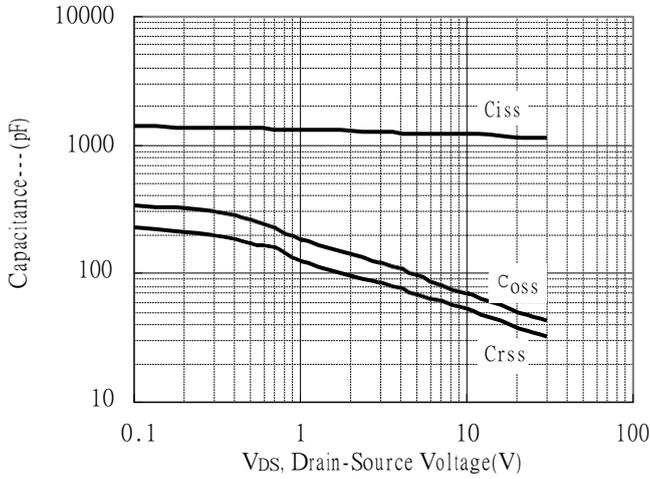


Drain-Source On-State Resistance vs Junction Temperature

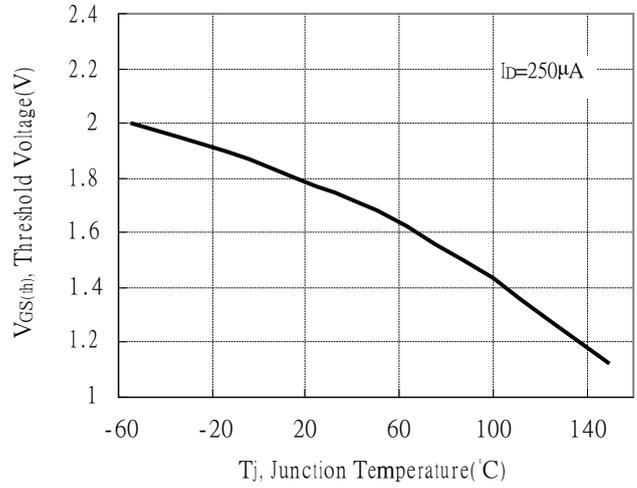


**Typical Characteristics(Cont.)**

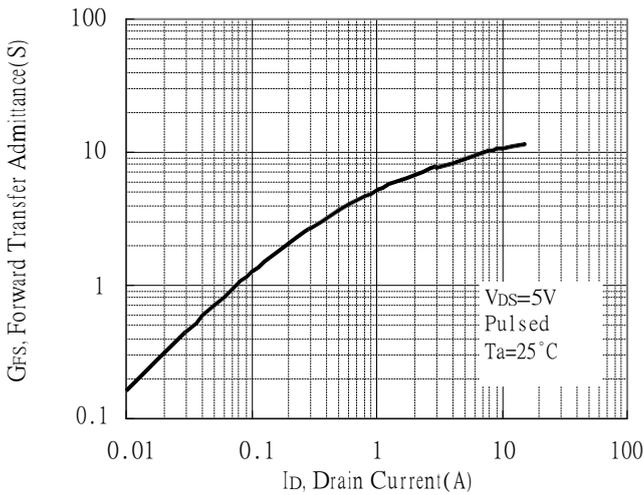
Capacitance vs Drain-to-Source Voltage



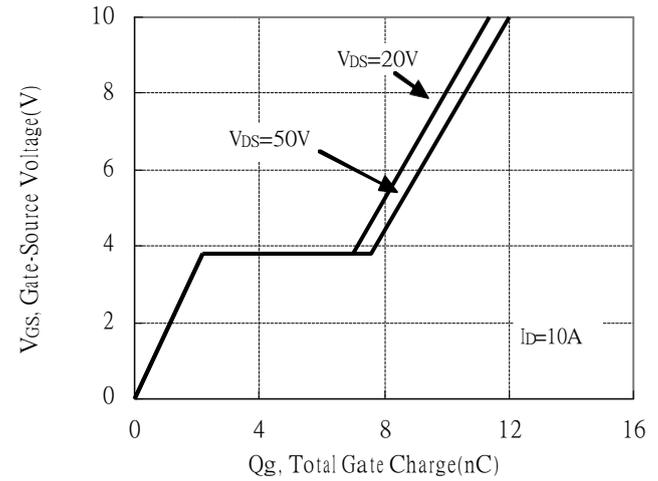
Threshold Voltage vs Junction Temperature



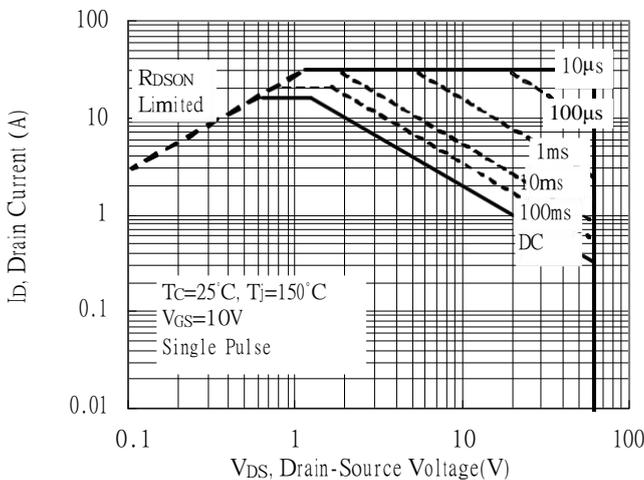
Forward Transfer Admittance vs Drain Current



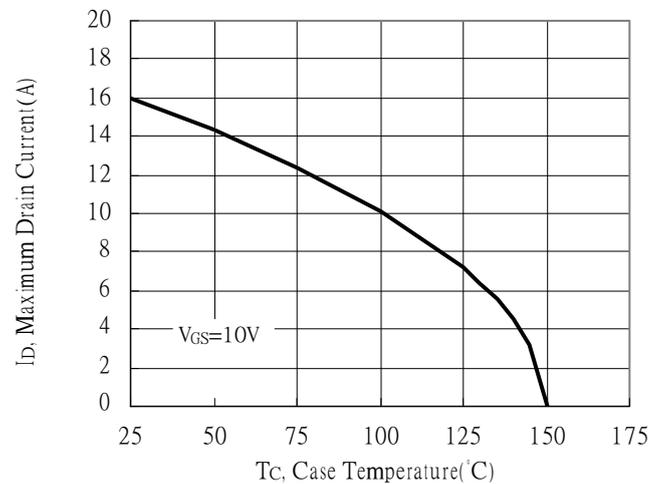
Gate Charge Characteristics



Maximum Safe Operating Area

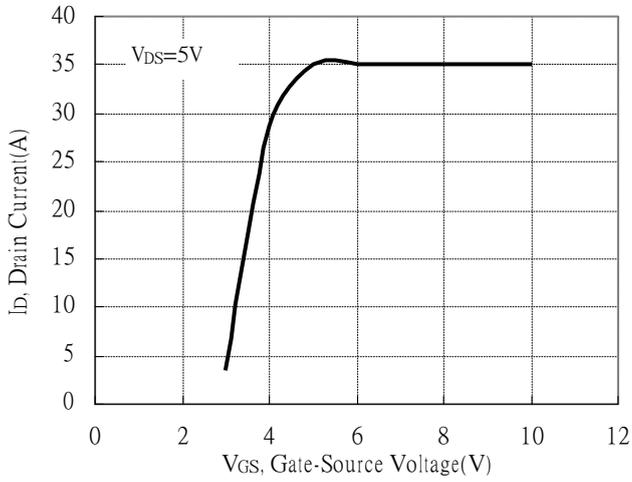


Maximum Drain Current vs Case Temperature

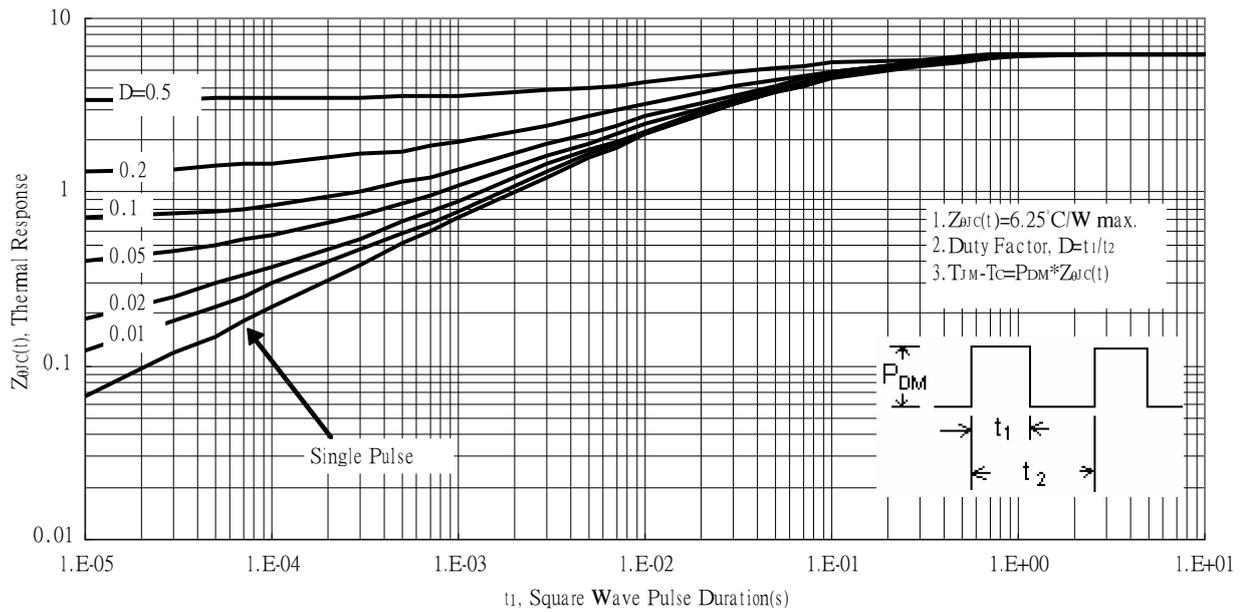


**Typical Characteristics(Cont.)**

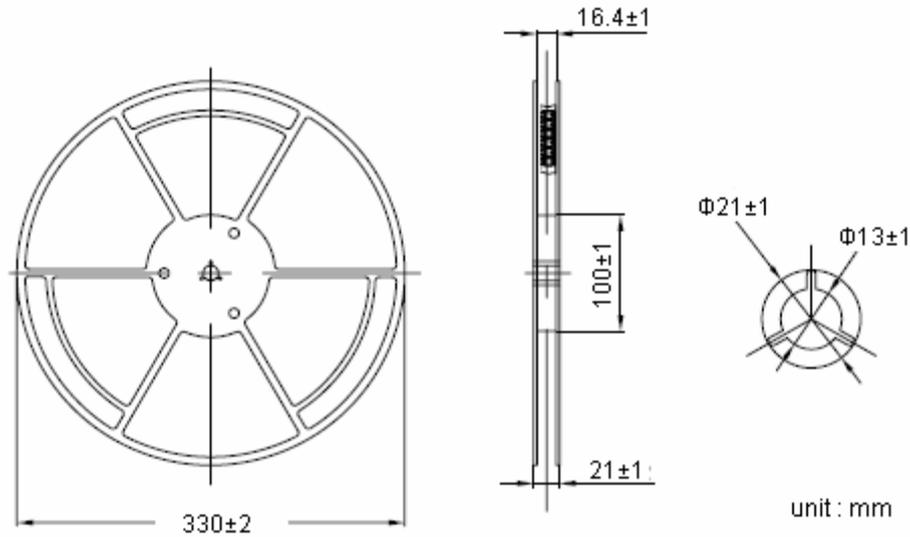
Typical Transfer Characteristics



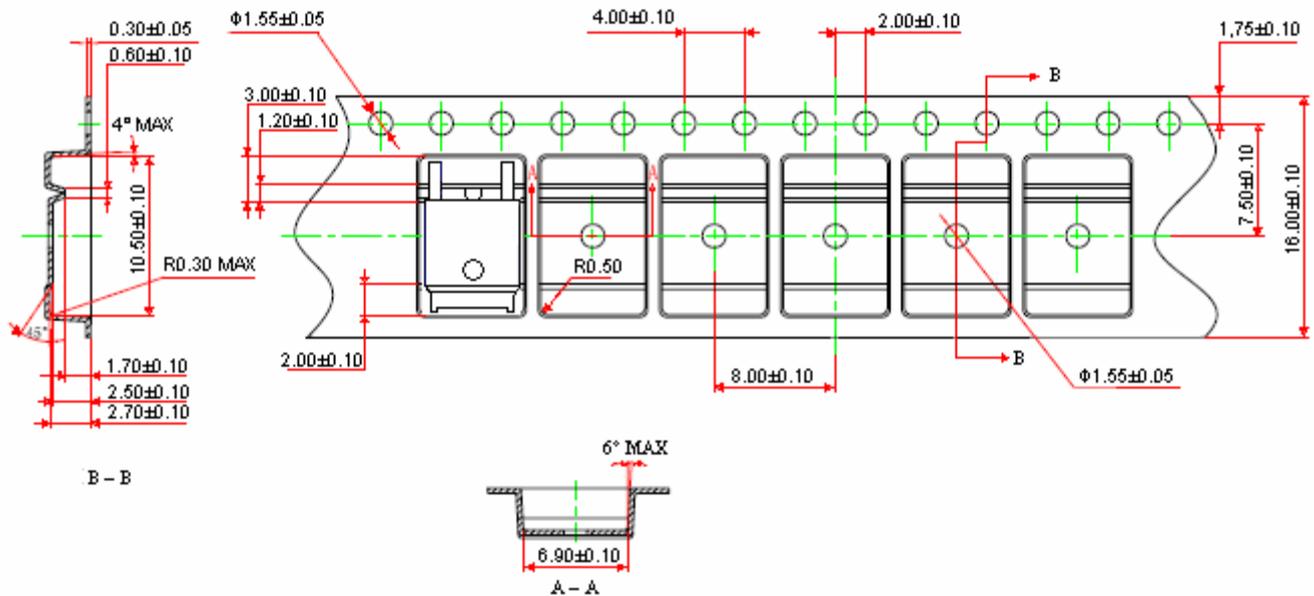
Transient Thermal Response Curves



### Reel Dimension



### Carrier Tape Dimension

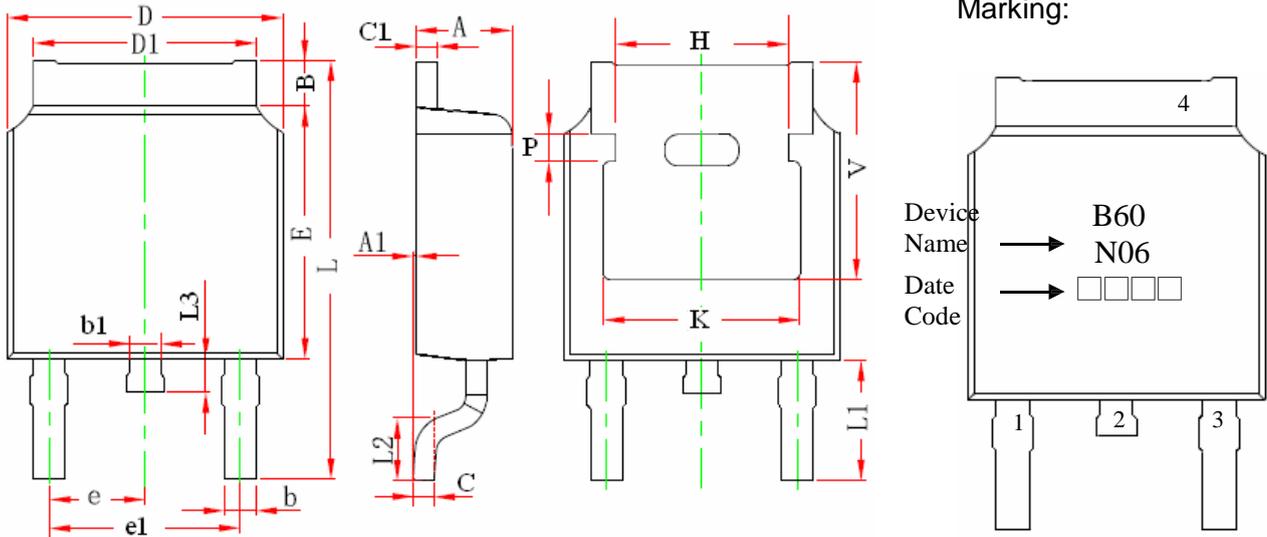


**Notes:**

1. 10 sprocket hole pitch cumulative tolerance  $\pm 0.2$ .
2. Camber not to exceed 1mm in 100mm.
3. Material: conductive black polystyrene, antistatic coated :  $10^5 \Omega/\square \sim 10^{11} \Omega/\square$

unit : mm

**TO-252 Dimension**



3-Lead TO-252 Plastic Surface Mount Package

Style: Pin 1.Gate 2.Drain 3.Source  
4.Drain

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	e	0.086	0.094	2.186	2.386
A1	0.000	0.005	0.000	0.127	e1	0.172	0.188	4.372	4.772
B	0.039	0.048	0.990	1.210	H	0.163	REF	4.140	REF
b	0.026	0.034	0.660	0.860	K	0.190	REF	4.830	REF
b1	0.026	0.034	0.660	0.860	L	0.386	0.409	9.800	10.400
C	0.018	0.023	0.460	0.580	L1	0.114	REF	2.900	REF
C1	0.018	0.023	0.460	0.580	L2	0.055	0.067	1.400	1.700
D	0.256	0.264	6.500	6.700	L3	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	P	0.026	REF	0.650	REF
E	0.236	0.244	6.000	6.200	V	0.211	REF	5.350	REF